



Dow Corning[®] TC-5121 C LV Thermally Conductive Compound

FEATURES & BENEFITS

- Optimized polymer matrix to help reduce pump out
- Flowable
- Good thermal conductivity
- Low thermal resistance
- Non-curing, no need for curing ovens
- Heat removal from electronics components
- Can achieve thin Bond Line Thickness (BLT)

COMPOSITION

- Filled polydimethylsiloxane

Greenish yellow, flowable, non-curing thermally conductive compound

APPLICATIONS

- Dow Corning[®] TC-5121 C LV Thermally Conductive Compound is suitable for use as an interface material for a variety of mid to high end electronic devices.

TYPICAL PROPERTIES

Specification Writers: These values are not intended for use in preparing specifications. Please contact your local Dow Corning sales office or your Global Dow Corning Connection before writing specifications on this product.

Test*	Property	Unit	Result
-	One part or Two part	-	One
-	Color	-	Greenish yellow
CTM 0050	Viscosity	Pa-sec	79.0
		cP	79000
CTM: 0905	Thixotropy	-	1.69
CTM: 0540	Specific Gravity (Uncured)	-	4.2
-	NVC (Non Volatile Content)	%	99.93
CTM: 1388	Thermal Conductivity	W/m-K	2.8
-	Thermal Resistance at 40 psi	°C-cm ² /W	0.09
CTM: 0114	Dielectric Strength	kV/mm	1.89
		Volts/mil	47.3
CTM: 1400	Volume resistivity	ohm*cm	1.3E+13
CTM: 1139	Dielectric Constant @ 1 kHz:	-	14.0
CTM: 1139	Dissipation Factor @ 1 kHz	-	0.073

*CTM: Corporate Test Method, copies of CTM's are available on request.

DESCRIPTION

Dow Corning[®] brand thermally conductive compounds are grease like silicone materials, heavily filled with heat-conductive metal oxides. This combination promotes high thermal conductivity, low bleed and high-temperature stability. The compounds are designed to maintain a positive

heat sink seal to improve heat transfer from the electrical/electronic device to the heat sink or chassis, thereby increasing the overall efficiency of the device. Electronic devices are continually designed to deliver higher performance. Especially in the area of consumer electronics, there is also a continual trend towards smaller, more

compact designs. In combination these factors typically mean that more heat is generated in the device. Thermal management of electronic devices is a primary concern of design engineers. A cooler device allows for more efficient operation and better reliability over the life of the device. As such, thermally conductive compounds play an integral role here. Thermally conductive materials act as a thermal “bridge” to remove heat from a heat source (device) to the ambient via a heat transfer media (i.e. heat sink). These materials have properties such as low thermal resistance, high thermal conductivity, and can achieve thin Bond Line Thicknesses (BLTs) which can help to improve the transfer of heat away from the device.

APPLICATION METHODS

- Screen print
- Stencil print
- Dispense

HOW TO USE

Allow printed grease pad to dry open for 24 hours before assembly. Dry time allows the small amount of carrier fluid to evaporate.

SOLVENT EXPOSURE

In general, the product is resistance to minimal or intermittent solvent exposure, however best practice is to avoid solvent exposure altogether.

HANDLING

PRECAUTIONS

PRODUCT SAFETY

INFORMATION REQUIRED FOR SAFE USE IS NOT INCLUDED IN THIS DOCUMENT. BEFORE HANDLING, READ PRODUCT AND SAFETY DATA SHEETS AND CONTAINER LABELS FOR SAFE USE, PHYSICAL AND HEALTH HAZARD INFORMATION. THE SAFETY DATA SHEET IS AVAILABLE ON THE DOW CORNING WEBSITE AT DOWCORNING.COM, OR FROM YOUR DOW CORNING SALES APPLICATION ENGINEER, OR DISTRIBUTOR,

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USABLE LIFE AND STORAGE

The product should be stored in its original packaging with the cover tightly attached to avoid any contamination. Store in accordance with any special instructions listed on the product label. The product should be used by the indicated Exp. Date found on the label.

LIMITATIONS

This product is neither tested nor represented as suitable for medical or pharmaceutical uses.

HEALTH AND ENVIRONMENTAL INFORMATION

To support customers in their product safety needs, Dow Corning has an extensive Product Stewardship organization and a team of Product Safety and Regulatory Compliance (PS&RC) specialists available in each area.

For further information, please see our website, dowcorning.com or consult your local Dow Corning representative.

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The information contained herein is offered in good faith and is believed to be accurate. However, because conditions and methods of use of our products are beyond our control, this information should not be used in substitution for customer’s tests to ensure that our products are safe, effective, and fully satisfactory for the intended end use. Suggestions of use shall not be taken as inducements to infringe any patent.

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